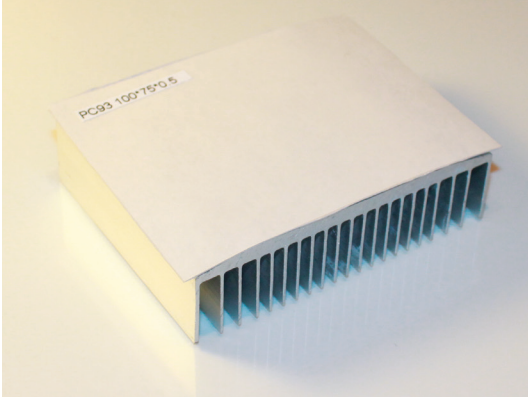


# PC93

## Non-Silicone Thermal Conductive Pad



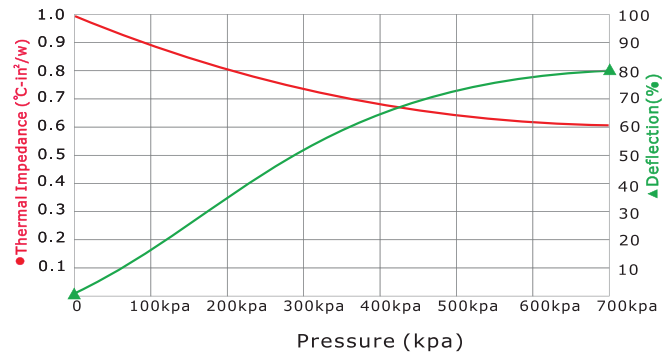
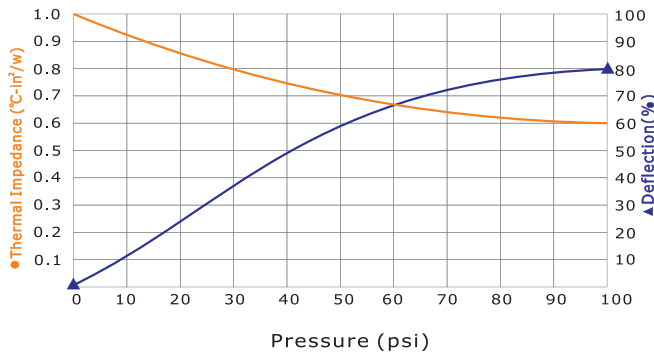
### Features

- Low contact thermal impedance
- Good thermal conductivity
- Silicone free
- Long term stability

### Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

### Thermal Resistance V.S Pressure V.S Deflection



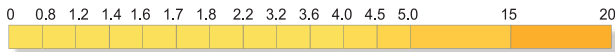
### Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 2 W/m.k  
(W / m.k - Z Axis)

Hardness: 60 (Shore 00)  
(Shore 00)

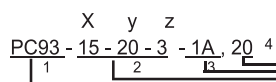


Testing sample thickness : 1.0 mm

In the thermal resistance vs pressure vs deflection charts PC93 provides low thermal impedance. As the pressure increases the thermal impedance decreases. PC93 provides good compliance and softness.

Property	PC93	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.25 ~ 5.0	mm	-	ASTM D374
	0.0098~0.1969	inch	-	ASTM D374
Thermal Conductivity	2	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	1.5	g/cm <sup>3</sup>	±0.2	ASTM D792
Working Temperature	-30~ 150	°C	-	-
Volume Resistance	>10 <sup>12</sup>	Ohm-cm	-	ASTM D257
Elongation	350	%	±13	ASTM D412
Tensile Strength	1	Kgf/mm <sup>2</sup>	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A-one side, 2A-two sides
4. Quantity